

# 3.3V CMOS 16-BIT IDT7 TRANSPARENT D-TYPE OBS LATCH WITH 3-STATE OUTPUTS, 5 VOLT TOLERANT I/O AND BUS-HOLD

# IDT74LVCH16373A OBSOLETE PART

# **FEATURES:**

- Typical tsk(o) (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- Vcc = 3.3V ± 0.3V, Normal Range
- Vcc = 2.7V to 3.6V, Extended Range
- CMOS power levels (0.4

  W typ. static)
- · All inputs, outputs, and I/O are 5V tolerant
- · Supports hot insertion
- · Available in TSSOP package

# DRIVE FEATURES:

- · High Output Drivers: ±24mA
- · Reduced system switching noise

# **APPLICATIONS:**

- 5V and 3.3V mixed voltage systems
- Data communication and telecommunication systems

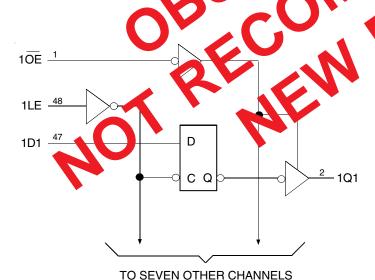
# **DESCRIPTION**

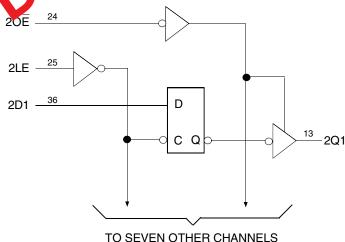
The LVCH16373A 16-bit transparent D-type latch is built using advanced dual metal CMOS technology. This high-speed, low-power latch is ideal for temporary storage of data. The LVCH16373A can be used for implementing memory address latches, I/O ports, and bus drivers. The Output Enable and Latch Enable controls are organized to operate each device as two 8-bit latches or one 16-bit latch. Flow-threagy organization of signal pins simplifies lag ut. All inputs are designed withing teresis for improved noise margin

All pins of the Liv SH2 4373A can be drive arrorm. There is 3V or 5V devices. This feature is two it is use of the device as a ranslator in a mixed 3.3V/5V supply as tell.

The LCH 6373A has "bus gold" which retains the inputs' last state whenever the input goes had lightly dedance. This prevents floating inputs and eliminates the new transput up/down resistors.

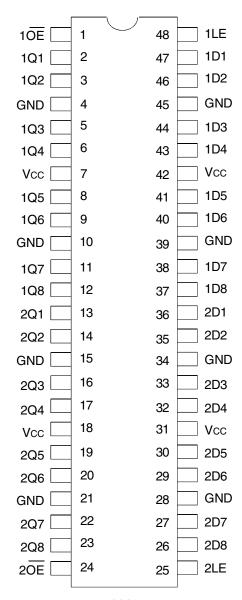
# FUNCTIONAL BLOCK DIL GI AM







# **PIN CONFIGURATION**



TSSOP TOP VIEW

# ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to +6.5	V
Tstg	Storage Temperature	-65 to +150	°C
lout	DC Output Current	-50 to +50	mA
lik lok	Continuous Clamp Current, VI < 0 or Vo < 0	-50	mA
lcc Iss	Continuous Current through each Vcc or GND	±100	mA

### NOTE:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

# CAPACITANCE (TA = +25°C, F = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	4.5	6	pF
Соит	Output Capacitance	Vout = 0V	6.5	8	pF
CI/O	I/O Port Capacitance	VIN = 0V	6.5	8	pF

### NOTE:

1. As applicable to the device type.

# **PIN DESCRIPTION**

Pin Names	Description	
хDх	Data Inputs <sup>(1)</sup>	
xLE	Latch Enable Input	
xŌĒ	Output Enable Inputs (Active LOW)	
хОх	3-State Outputs	

### NOTE:

1. These pins have "Bus-Hold". All other pins are standard inputs, outputs, or I/Os.

# FUNCTION TABLE(1)

	Inputs		
хDх	xLE	х <mark>ОЕ</mark>	хQх
Н	Н	L	Н
L	Н	L	L
Х	L	L	Q <sup>(2)</sup>
Х	Х	Н	Z

### NOTES:

- 1. H = HIGH Voltage Level
  - X = Don't Care
  - L = LOW Voltage Level
  - Z = High-Impedance
- 2. Output level before the indicated steady-state input conditions were established.



# IDT74LVCH16373A 3.3VCMOS16-BITTRANSPARENTD-TYPELATCH

# DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition:  $TA = -40^{\circ}C$  to  $+85^{\circ}C$ 

Symbol	Parameter	Test Cor	nditions	Min.	Typ. <sup>(1)</sup>	Max.	Unit
ViH	Input HIGH Voltage Level	Vcc = 2.3V to 2.7V		1.7	_	_	V
		Vcc = 2.7V to 3.6V		2	_	_	
VIL	Input LOW Voltage Level	Vcc = 2.3V to 2.7V		_	_	0.7	V
		Vcc = 2.7V to 3.6V		_	_	0.8	
Іін	Input Leakage Current	Vcc = 3.6V	VI = 0 to 5.5V	_	_	±5	μA
lıL							
lozн	High Impedance Output Current	Vcc = 3.6V	Vo = 0 to 5.5V	_	_	±10	μA
lozl	(3-State Output pins)						
loff	Input/Output Power Off Leakage	$VCC = 0V$ , $VIN or VO \le 5.5V$		_	_	±50	μA
Vik	Clamp Diode Voltage	VCC = 2.3V, IIN = -18mA		_	-0.7	-1.2	V
VH	Input Hysteresis	Vcc = 3.3V		T -	100	_	mV
ICCL	Quiescent Power Supply Current	VCC = 3.6V	VIN = GND or VCC	_	_	10	μΑ
Iссн Iссz		$3.6 \le VIN \le 5.5V^{(2)}$		<del> </del>	_	10	
∆lcc	Quiescent Power Supply Current Variation	One input at Vcc - 0.6V, other in	nputs at Vcc or GND	_		500	μΑ

# NOTES:

- 1. Typical values are at Vcc = 3.3V, +25°C ambient.
- 2. This applies in the disabled state only.

# **BUS-HOLD CHARACTERISTICS**

Symbol	Parameter <sup>(1)</sup>	Test Conditions		Min.	Typ. <sup>(2)</sup>	Max.	Unit
Івнн	Bus-Hold Input Sustain Current	Vcc = 3V	VI = 2V	<b>-</b> 75	_	_	μΑ
IBHL			VI = 0.8V	75	_	_	
Івнн	Bus-Hold Input Sustain Current	Vcc = 2.3V	VI = 1.7V	_	_	_	μΑ
IBHL			VI = 0.7V	_	_	_	
Івнно	Bus-Hold Input Overdrive Current	Vcc = 3.6V	VI = 0 to 3.6V	_	_	±500	μΑ
Івньо							

# NOTES:

- 1. Pins with Bus-Hold are identified in the pin description.
- 2. Typical values are at Vcc = 3.3V, +25°C ambient.



# IDT74LVCH16373A 3.3VCMOS16-BITTRANSPARENTD-TYPE LATCH

# **OUTPUT DRIVE CHARACTERISTICS**

Symbol	Parameter	Test Con	ditions <sup>(1)</sup>	Min.	Max.	Unit
Vон	Output HIGH Voltage	Vcc = 2.3V to 3.6V	IOH = - 0.1mA	Vcc-0.2	_	V
		Vcc = 2.3V	IOH = -6mA	2	_	
		Vcc = 2.3V	Iон = - 12mA	1.7	_	
		Vcc = 2.7V		2.2	_	
		VCC = 3V		2.4	_	
		Vcc = 3V	IOH = - 24mA	2.2	_	
Vol	Output LOW Voltage	Vcc = 2.3V to 3.6V	IoL = 0.1mA	_	0.2	V
		Vcc = 2.3V	IoL = 6mA	_	0.4	
			IoL = 12mA	_	0.7	
		Vcc = 2.7V	IoL = 12mA	_	0.4	
		VCC = 3V	IOL = 24mA	1	0.55	

### NOTF:

# OPERATING CHARACTERISTICS, Vcc = 3.3V ± 0.3V, Ta = 25°C

Symbol	Parameter	Test Conditions	Typical	Unit
CPD	Power Dissipation Capacitance per Latch Outputs enabled	CL = 0pF, f = 10Mhz	39	pF
CPD	Power Dissipation Capacitance per Latch Outputs disabled		6	

# SWITCHING CHARACTERISTICS(1)

		Vcc =	= 2.7V	Vcc = 3.3	V ± 0.3V	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
tplH	Propagation Delay	_	4.9	1.6	4.2	ns
tphL tphL	xDx to xQx					
tplH	Propagation Delay	_	5.3	2.1	4.6	ns
tphL tphL	xLE to xQx					
tpzh	Output Enable Time	_	5.7	1.3	4.7	ns
tpzL	xOE to xQx					
tphz	Output Disable Time	_	6.3	2.5	5.9	ns
tplz	xOE to xQx					
tsu	Set-up Time, data before LE↓HIGH or LOW	1.7	_	1.7	_	ns
tH	Hold Time, data after LE↓ HIGH or LOW	1.2	_	1.2	_	ns
tw	Pulse Width xLE HIGH	3.3	_	3.3	_	ns
tsk(o)	Output Skew <sup>(2)</sup>	_	_	_	500	ps

### NOTES:

- 1. See TEST CIRCUITS AND WAVEFORMS.  $TA = -40^{\circ}C$  to  $+85^{\circ}C$ .
- 2. Skew between any two outputs of the same package and switching in the same direction.

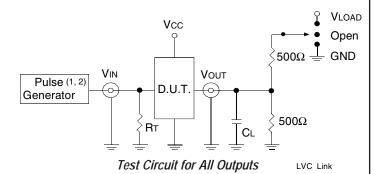
<sup>1.</sup> VIH and VIL must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate Vcc range. TA = - 40°C to + 85°C.



# TEST CIRCUITS AND WAVEFORMS

# **TEST CONDITIONS**

Symbol	$Vcc^{(1)} = 3.3V \pm 0.3V$	Vcc <sup>(1)</sup> =2.7V	Vcc <sup>(2)</sup> =2.5V±0.2V	Unit
VLOAD	6	6	2 x Vcc	V
VIH	2.7	2.7	Vcc	V
VT	1.5	1.5	Vcc / 2	V
VLZ	300	300	150	mV
VHZ	300	300	150	mV
CL	50	50	30	pF



### **DEFINITIONS:**

CL = Load capacitance: includes jig and probe capacitance.

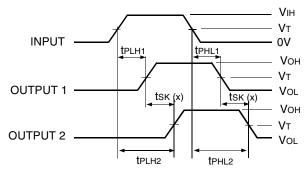
RT = Termination resistance: should be equal to ZouT of the Pulse Generator.

### NOTES:

- 1. Pulse Generator for All Pulses: Rate  $\leq$  10MHz: tF  $\leq$  2.5ns: tR  $\leq$  2.5ns.
- 2. Pulse Generator for All Pulses: Rate  $\leq$  10MHz; tF  $\leq$  2ns; tR  $\leq$  2ns.

# **SWITCH POSITION**

Test	Switch
Open Drain Disable Low Enable Low	VLOAD
Disable High Enable High	GND
All Other Tests	Open

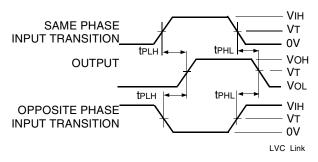


tsk(x) = |tplh2 - tplh1| or |tphl2 - tphl1|

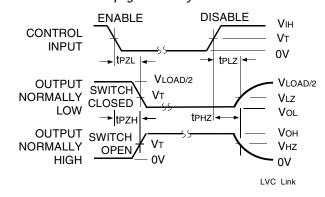
Output Skew - tsk(x)

## NOTES:

- For tsk(o) OUTPUT1 and OUTPUT2 are any two outputs.
- For tsk(b) OUTPUT1 and OUTPUT2 are in the same bank.

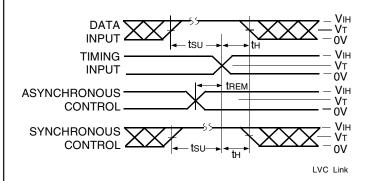


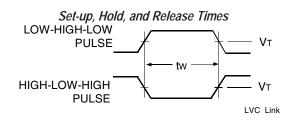
# Propagation Delay



# Enable and Disable Times

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.





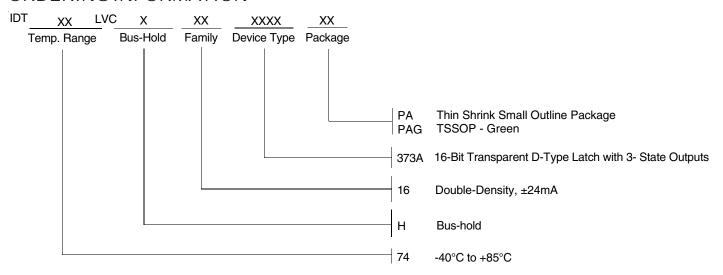
Pulse Width

LVC Link



IDT74LVCH16373A 3.3VCMOS16-BITTRANSPARENTD-TYPE LATCH

# ORDERING INFORMATION



# **DATASHEET DOCUMENT HISTORY**

07/13/2015 PDN# CQ-14-05 issued. See IDT.com for PDN specifics.

09/06/2019 Datasheet changed to Obsolete Status.

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